ABSTRACT

CHIP SCALE PACKAGE WITH OPEN SUBSTRATE

An integrated circuit package comprises a substrate including a core layer with a through opening and vias. A first conductive layer is on the core layer covering the through opening and a second conductive layer is on the core layer opposite the first conductive layer in the through opening and in the vias contacting the first conductive layer. An integrated circuit die is bonded to the second conductive layer and in the through opening. Connections are between the integrated circuit die and the second conductive layer, and the integrated circuit die and the connections are encapsulated. (Fig. 1)